

REMARKS

By this amendment claims 1-4, 9, 11, 12, and 14 have been amended, claims 5 and 8 have been canceled, and claims 20-23 have been added. Claims 1-4, 6, 7, and 9-23 remain pending. Reconsideration of the application as amended is respectfully requested.

Rejection under 35 USC §102(e)

Remaining claims 1-7, 11-13, and 19 have been rejected under 35 USC §102(e) as being anticipated by Motoooka et al. (US 6,207,477). Motoooka discloses a method of forming a semiconductor device including providing a wafer having at least a first and second die, at least one conductive pad on each die, a kerf area (51) interposed between each die, providing bond wires (4) attached to the dies and the kerf area, encapsulating the bond wires, the conductive pads, and the kerf area, and dicing the wafer at the kerf area (see FIGS. 5A-F and related text).

The rejected claims as amended comprise novel and nonobvious differences over the disclosure of Motoooka. Claim 1, for example, recites "...dicing in the kerf area to separate the first die from the second die; and during the dicing in the kerf area, cutting the bond wire." Motoooka fails to teach or suggest such a process, and thus claim 1, and rejected claims 2 and 3 which depend therefrom, are allowable over Motoooka for at least this reason.

Claim 8, which was objected to by the Examiner, and intervening claim 5 have been written into independent claim 4 and canceled. Thus claim 4 and claims 6, 7, and 9-11 which depend therefrom, are allowable over Motoooka.

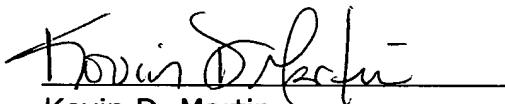
Claim 12 has been amended to include the recitation "...during the segmenting of the first semiconductor wafer section from the second semiconductor wafer section, removing at least a portion of the kerf area and the bond wire." This added recitation has been written into claim 12 from claim 14 which has been objected to. It is believed the amendment renders claim 12 allowable as the Examiner has indicated in the reasons for allowance that "none of the prior art teaches or suggesting cutting the bond wires or exposing the bond wires due to the dicing of the wafer." Thus claim 12 and claims 13-19 which depend therefrom are believed to be allowable under 35 USC §102(e) over Motoooka for at least this reason.

Newly added claims 20-23 are believed to be allowable over the cited art. Claim 20 recites "...during the separation of the first semiconductor die from the second semiconductor die, removing a portion of the bond wire," which is believed to be neither taught nor suggested by the cited art. Claims 20-23 are therefore allowable.

Conclusion

For the foregoing reasons, the application is believed to be in condition for allowance. If there are matters which may be resolved or clarified through a telephone conversation, the Examiner is cordially invited to contact the undersigned. This is believed to be a complete response to the Examiner's office action.

Respectfully submitted,



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